Additional Testing Facility

DiskOnChip G3 64MByte (512Mbit) and 128MByte (1Gbit) FBGA

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Description

The AMKOR Japan testing facility, which is already used as the assembly site for DiskOnChip G3 products, will be used to test, mark and pack DiskOnChip 7x10 and 9x12 FBGA products that are manufactured by Toshiba. Until now, DiskOnChip FBGA products have been tested at the Yokkaichi Toshiba Electronics (YTE) and PowerTech Technology (PTI) testing facilities.

AMKOR Japan is an approved testing facility for M-Systems and Toshiba, and the same test equipment currently used at YTE in Japan will be used by AMKOR Japan.

The affected DiskOnChip G3 7x10 and 9x12 FBGA products will continue to be manufactured and assembled at the YTE and AMKOR plants in Japan.

The assembly sites for DiskOnChip G3 7x10 and 9x12 FBGA products will be YTE and AMKOR Japan, and the testing, marking, and packing processes will be performed at the YTE, PTI, and AMKOR sites.

Ordering Information

The following products are affected:

Product	Form Factors	Capacity (MB)	Ordering Information
DiskOnChip G3	7x10 FBGA	64MByte (512Mbit)	MD4832-d512-V3Q18-X MD4832-d512-V3Q18-X-P
DiskOnChip G3	9x12 FBGA	128MByte (1Gb)	MD4331-d1G-V3Q18-X MD4331-d1G-V3Q18-X-P

Reason for Change

The location of the testing facility for the abovementioned DiskOnChip products is being changed due to M-Systems' increased production requirements, which in turn created a need for a testing facility with greater capacity.

Timetable

Products will be tested at the new location according to the following schedule:

Product	Ordering Information	Schedule
DiskOnChip G3	MD4832-d512-V3Q18-X MD4832-d512-V3Q18-X-P	December 2004
	MD4331-d1G-V3Q18-X MD4331-d1G-V3Q18-X-P	December 2004

Quality Assurance Procedure

Overall responsibility for quality assurance and quality control procedures will remain under the auspices of YTE in Japan. M-Systems and Toshiba are working closely to ensure a smooth changeover to the alternative testing facility. The following actions will be implemented:

- Correlation testing between the current and new testing sites.
- Functional tests of the tested devices by both Toshiba and M-Systems.
- Extended monitoring of the first manufacturing lots that are tested at the new testing site.
- M-Systems performed an on-site Quality Assurance audit of the AMKOR site, which was subsequently approved as an authorized testing facility.

Full traceability of product assembly and testing is assured.

How to Contact Us

Please contact your M-Systems representative or visit the DiskOnChip web page on the M-Systems website (www.m-systems.com) for any further information or assistance.

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